



Diameter Size: **105 mm**  
 Thickness: **1,6 mm**  
 Weight: **36 g**  
 Electricity Line: **Copper**  
 Thickness of copper: **35um**  
 Thickness of the dielectric: **70um**  
 Thickness of the aluminum-base: **1.5mm**

**Lenses for PCB 724-102:**



18 B 30 D



18 B 50 D



18 B 3570 D

The result of the test:

Item	Test item	Technology request	Unit	Test result	
1	Peel Strength	A	≥1.8	N/mm	2.0
		After thermal stress ( 260°C )	≥1.8	N/mm	1.8
2	Blister test After Thermal stress ( 288°C , 2min )	288°C, 2 min No delaminating	/	Ok	
3	Thermal resistance	≤2.0	°C/W	1.0	
4	Thermal-Conductive Factor		W/m-k	1.0	
5	Flammability(A)	FV-O	/	FV-O	
6	Surface Resistivity	A	≥ 1×10 <sup>5</sup>	MΩ	5×10 <sup>7</sup>
		Constant humidity treatment (90%,35°C,96h)	≥ 1×10 <sup>5</sup>	MΩ	2×10 <sup>6</sup>
7	Volume Resistivity	A	≥ 1×10 <sup>6</sup>	MΩ·m	4×10 <sup>8</sup>
		Constant humidity treatment (90%,35°C,96h)	≥ 1×10 <sup>6</sup>	MΩ·m	5×10 <sup>7</sup>
8	Dielectric Breakdown(DC)	≥ 28.5	KV/MM	31	
9	Dielectric constant(1MHz) (40°C, 93%, 96h)	≤4.4	/	4.2	
10	Dielectric dissipation factor (1MHz) (40°C , 93% , 96h)	≤0.03	/	0.02	

